L	Hits	Search Text	DB	Time stamp
Number	_			0004/05/15
-	2	("6664621").PN.	USPAT;	2004/06/16
			US-PGPUB;	12:43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	66060	microelectronic	USPAT;	2004/06/16
			US-PGPUB;	12:43
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	543	microelectronic and interconnect and	USPAT;	2004/06/16
	343	(active same microelectronic)	US-PGPUB;	12:44
		(active same microerectionic)	EPO; JPO;	12.33
1			DERWENT;	
			IBM_TDB	
<u> </u>	352	(microelectronic and interconnect and	USPAT;	2004/06/16
Ì		(active same microelectronic)) and	US-PGPUB;	12:44
		(terminal or lead)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
l <b>-</b>	23	((microelectronic and interconnect and	USPAT;	2004/06/16
		(active same microelectronic)) and	US-PGPUB;	12:49
			EPO; JPO;	1 -6.37
		(terminal or lead)) and ((terminal or		
		lead) same (movable or moveable))	DERWENT;	
			IBM_TDB	
-	22	(((microelectronic and interconnect and	USPAT;	2004/06/16
		(active same microelectronic)) and	US-PGPUB;	12:50
1		(terminal or lead)) and ((terminal or	EPO; JPO;	
1		lead) same (movable or moveable))) and	DERWENT;	
		(copper or cu or gold or au or ag or	IBM TDB	1
İ		silver)	_	
_	8	((((microelectronic and interconnect and	USPAT;	2004/06/16
		(active same microelectronic)) and	US-PGPUB;	12:50
		(terminal or lead)) and ((terminal or	EPO; JPO;	
		lead) same (movable or moveable))) and	DERWENT;	
		(copper or cu or gold or au or ag or	IBM TDB	
		(copper of cu of gold of au of ag of   silver)) and (interconnect same (copper	I DIM _ I DID	
		or cu or gold or au or ag or silver))		0004/05/15
-	63	((microelectronic and interconnect and	USPAT;	2004/06/16
		(active same microelectronic)) and	US-PGPUB;	12:49
		(terminal or lead)) and ((terminal or	EPO; JPO;	
		lead) same (movable or moveable or	DERWENT;	
l		flexible or frangible))	IBM_TDB	
-	60	(((microelectronic and interconnect and	USPĀT;	2004/06/16
-		(active same microelectronic)) and	US-PGPUB;	12:50
		(terminal or lead)) and ((terminal or	EPO; JPO;	
İ		lead) same (movable or moveable or	DERWENT;	
		flexible or frangible))) and (copper or	IBM TDB	
		cu or gold or au or ag or silver)		
_	27		USPAT;	2004/06/16
-	2,	(active same microelectronic)) and	US-PGPUB;	13:03
		, ,	,	13.03
		(terminal or lead)) and ((terminal or	EPO; JPO;	
		lead) same (movable or moveable or	DERWENT;	
		flexible or frangible))) and (copper or	IBM_TDB	
	1	cu or gold or au or ag or silver)) and		
		(interconnect same (copper or cu or gold		
		or au or ag or silver))		
-	20	((((microelectronic and interconnect and	USPAT;	2004/06/16
		(active same microelectronic)) and	US-PGPUB;	13:05
		(terminal or lead)) and ((terminal or	EPO; JPO;	
		lead) same (movable or moveable or	DERWENT;	
			IBM TDB	į i
		flexible or frangible))) and (copper or	TBM_TDB "	
		cu or gold or au or ag or silver)) and		1
		(interconnect same (copper or cu or gold		
		or au or ag or silver))) and (438/\$.ccls.		
		or 257/\$.ccls.)	1	1

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-	14	<pre>((((((microelectronic and interconnect and (active same microelectronic)) and (terminal or lead)) and ((terminal or lead) same (movable or moveable or flexible or frangible))) and (copper or</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/16 13:05
		cu or gold or au or ag or silver)) and (interconnect same (copper or cu or gold or au or ag or silver)) and (438/\$.ccls. or 257/\$.ccls.)) and pad and (bond\$3 near10 (pressure or force))		
-	14	<pre>(((((((microelectronic and interconnect and (active same microelectronic)) and (terminal or lead)) and ((terminal or lead) same (movable or moveable or flexible or frangible))) and (copper or cu or gold or au or ag or silver)) and (interconnect same (copper or cu or gold</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16
		or au or ag or silver))) and (438/\$.ccls. or 257/\$.ccls.)) and pad and (bond\$3 near10 (pressure or force))) and bump		